



Product / Process Change Notice

No.: Z200-PCN-DM201603-04-A

Date: 03/31/2016

Change Title : Winbond SLC 1Gb NAND migration from W29N01GV to W29N01HV

Change Classification: Major Minor

Change item : Design Raw Material Wafer FAB Package Assembly Testing Others

Affected Product(s) :

W29N01GVBIAA , W29N01GVDIAA , W29N01GVSIAA

Description of Change(s)

Technology migration from W29N01GV to W29N01HV for Winbond SLC 1Gb NAND.

Reason for Change(s) :

According to Winbond product roadmap, launch new product W29N01HV.

Impact of Change(s) : (positive & negative)

Form : No Change

Fit : No Change

Function : No Concern (Please refer to attachment I)

Reliability : No Concern (Please refer to attachment II)

Hazardous Substances: No Concern (Please refer to attachment III)

Qualification Plan/ Results :

Base on Winbond Reliability report, the new product meets our criteria and no quality concern. (please refer to attachment II)

Implementation Plan :

The follow-up disposition of SLC 1Gb W29N01GV :

- 1) The date of Last-buy orders is Jun/30/2016.
- 2) The last shipment date is Sep/30/2016

Date Code: ____ onward Lot No: ____ onward Proposed first ship date: 06/30/2016

Originator: (QA Sec. Manager)

Approval: (QA Dept. Manager)

Approval: (QRA Director)

Contact for Questions & Concerns

Name: Betty Huang TEL:886-3-5678168 (ext.86549) FAX: 886-3-5796124
Address : # 539, Sec. 2, Wenxing Rd., Jhubei City, Hsinchu County 302, Taiwan
E-mail: Hyhuang8@winbond.com



Customer Comments:

Note: Please sign this notice, and return to Winbond contact within 30 days. If no response is received within 30 days, this Change Request will be assumed to meet your approval.

Approval Disapproval Conditional Approval : _____.

Comment:

Date: _____

Dept. name: _____

Person in charge: _____